

ABSTRACT

A wire bonding machine is disclosed for bonding a wire to a semiconductor device. The wire bonding machine includes a wire bonding head having a bonding tool mounted to it. The bonding tool is adapted to attach a wire end to a semiconductor device. At least a portion of the bonding head is pivotable about a first horizontal axis so as to provide vertical displacement of the bonding tool. The bonding head is also rotatably mounted to the bonding machine so as to permit rotation of the bonding tool about a vertically oriented rotational axis. The machine also includes a work table for supporting at least one semiconductor device to be wire bonded. A conveyance system is used to translate the work table in a direction relative to the bonding head and in a substantially orthogonal direction to the horizontal pivot axis of the bonding head.